



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



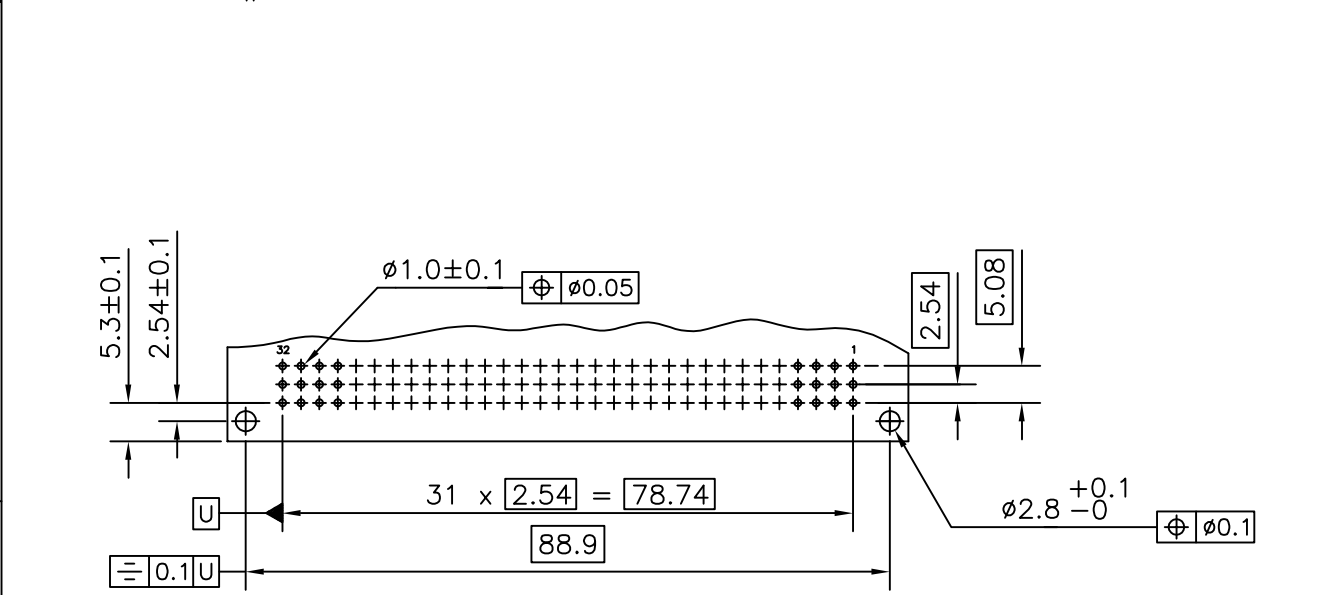
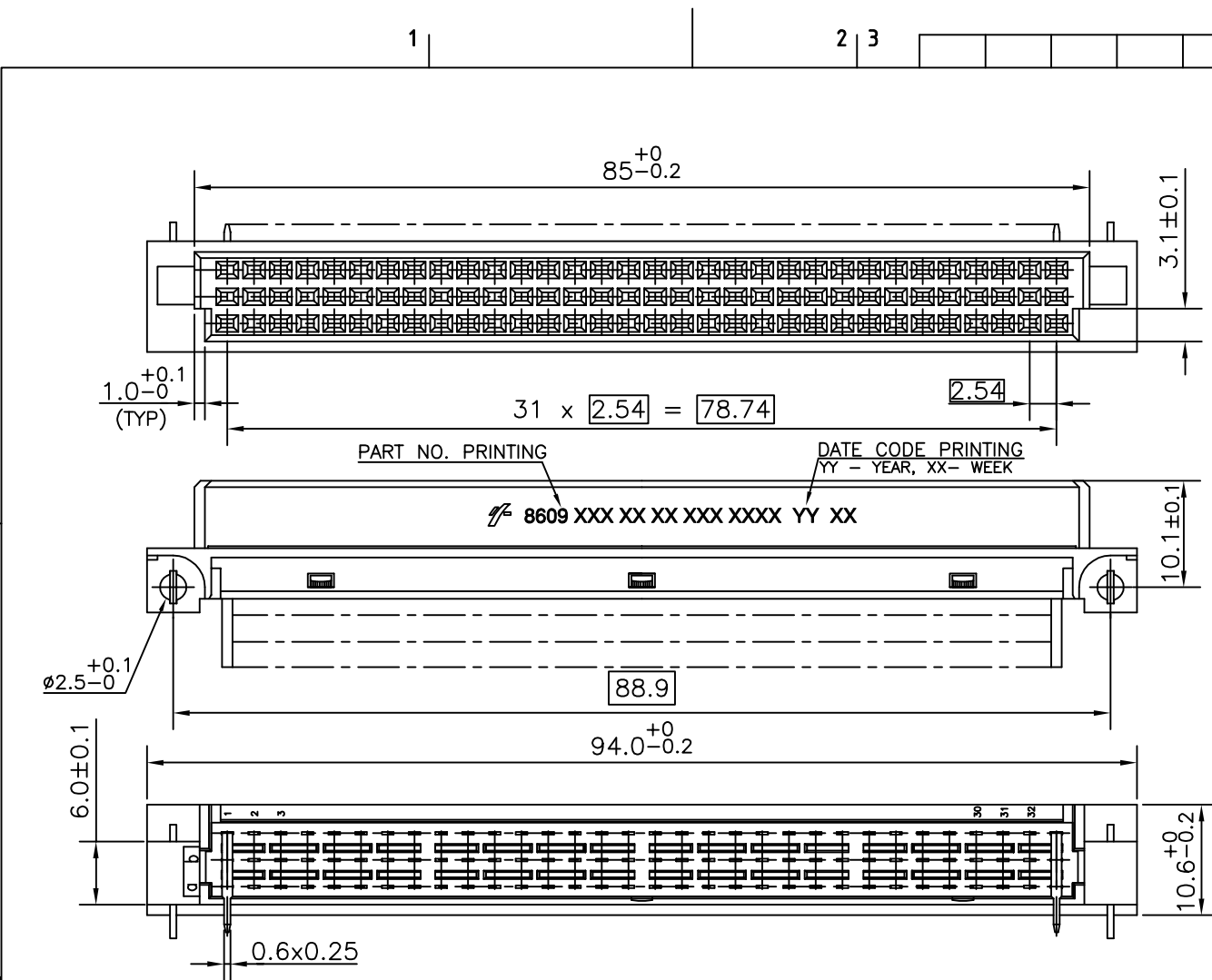
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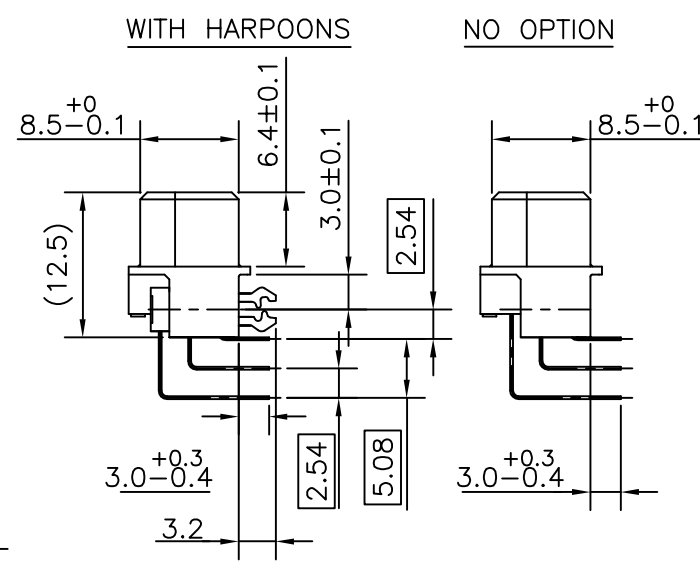




PCB DRILLING DETAILS

NOTES:-

1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD
3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.



TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V-0, GREY

HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR RIGHT ANGLE CONNECTORS AS IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C

CONTACT / HARPOON MATERIAL : COPPER ALLOY

CONTACT ACTIVE ZONE PLATING : GOLD OVER NICKEL

CONTACT TERMINATION ZONE / HARPOON PLATING

TIN LEAD VERSION : TIN LEAD OVER NICKEL

LEAD FREE VERSION : TIN (PURE MATTE) OVER Ni

ELECTRICAL DATA

CURRENT RATING AT 20°C : 1.5 A

CURRENT (I MAX) : 2 A

TEMPERATURE RANGE : -55°C/+125°C

CONTACT RESISTANCE : ≤ 20mΩ

INSULATION RESISTANCE : ≥ 10⁶ MΩ

TEST VOLTAGE (rms) : 1000V

MECHANICAL DATA

INSERTION FORCE PER CONTACT : ≤ 0.94N

EXTRACTION FORCE PER CONTACT : ≥ 0.15N

REFERENCE SPECIFICATIONS : NF C 93-429 / IEC 603-2

SERIES	8609	3	96	8	9	13	H	5	5	V1
ROWS FITTED WITH CONTACTS										
Rows a-b	---	2	64							
Rows a-b-c	---	3	96							
Rows a-c	---	4	64							
NUMBER OF CONTACTS										
TYPE OF INSULATOR										
3 ROW FEMALE INSULATOR	---	8								
METHOD OF MOUNTING										
REVERSE MOUNTING STYLE -HE 11	---	9								
TERMINATION										
ANGLED SPILL	---	13								
OPTIONS										
NO OPTION	---	7								
WITH HARPOONS	---	H								
PERFORMANCE CLASS										
NF C 93-429 CLASS 3	---	4								
NF C 93-429 CLASS 2	---	5								
NF C 93-429 CLASS 1	---	6								
AS PER MIL C 55302/ JSS 50808	---	8								
PITCH PER ROW										
2.54	---	5								
V1	---									TIN LEAD VERSION
V1LF	---									LEAD FREE VERSION

mat'l. code				surface		tolerance		projection		product family									
-				ISO 1302		ISO 406 ISO 1101				8609									
ltr	ecn no	dr	date	tolerances unless otherwise specified						title									
A	I05-0107	MINI	19/05/2005	angles	linear	.0±.1		mm		HE11 RECEPTACLE									
B	I06-0063	MINI	01/06/2006							ANGLED SPILL STYLE-HE11									
				0°±1°				scale -											
				dr	MINI K VANDANATH		29/09/2004				dwg no		sheet 1 of 1				size		
				engr	RAKHEE GEORGE		29/09/2004				C-8609-2030		A3						
				chr	RAKHEE GEORGE		01/06/2006												
				appd	RAKHEE GEORGE		01/06/2006												
sheet index		revision		B															
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